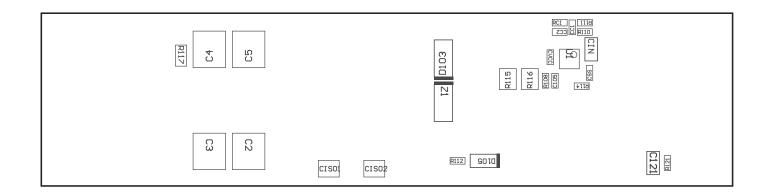


## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP9334	REV: C	SVN REV	: Not In VersionControl
	TID #: PMP9334			
PLOT NAME = Top Assembly Drawing	GENERATED : 5/8/20	016 8:32:15	PM	TEXAS INSTRUMENTS



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP9334	REV: C	SVN REV:	: Not In VersionControl		
	TID #: PMP9334					
PLOT NAME = Bottom Assembly Drawing	GENERATED : 5/8/20	016 8:32:16	PM	TEXAS INSTRUMENTS		

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